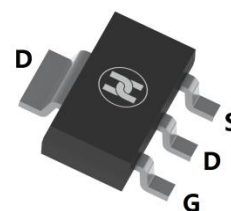
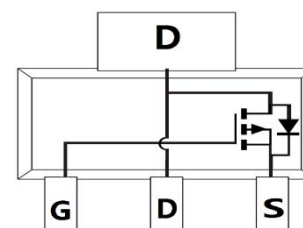


P-CHANNEL HIGH VOLTAGE MOSFET
FEATURES

- $V_{DS}=-100V, R_{DS(ON)} \leq 350m\Omega @ V_{GS}=-10V, I_D=-2.4A$
- Fast Switching Speed
- Low Input Capacitance and Low Gate Drive
- For Power Management Functions and DC-DC Converters
- For Motor Control, Relay and Solenoid Driving
- Surface Mount device

MECHANICAL DATA

- Case: SOT-223
- Case Material: Molded Plastic. UL flammability
- Classification Rating: 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Weight: 0.112 grams (approximate)


SOT-223

MAXIMUM RATINGS ($T_A = 25^\circ C$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-source voltage	V_{DS}	-100	V
Gate-source voltage	V_{GS}	± 20	V
Continuous drain current	I_D	$V_{GS}=-10V, T_A=25^\circ C(2)$	-2.4
		$V_{GS}=-10V, T_A=70^\circ C(2)$	-1.9
		$V_{GS}=-10V, T_A=25^\circ C(1)$	-1.7
Pulsed drain current(3)	I_{DM}	-9.4	A
Continuous Source Current (Body Diode)(2)	I_S	-4.5	A
Pulsed Source Current (Body Diode)(3)	I_{SM}	-9.4	A
Power dissipation(1)	P_D	2	W
Power dissipation(2)		3.9	W
Thermal Resistance, Junction to Ambient (1)	$R_{\theta JA}$	62.5	$^\circ C/W$
Thermal Resistance, Junction to Ambient (2)		32	$^\circ C/W$
Thermal Resistance, Junction to Case(4)	$R_{\theta JC}$	7.7	$^\circ C/W$
Operating and Storage temperature	T_J, T_{STG}	-55 ~ +150	$^\circ C$

ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ C$ unless otherwise specified)

Parameter	Symbol	Min	Typ	Max	Unit	Conditions
Drain-Source breakdown voltage	$V_{(BR)DSS}$	-100			V	$V_{GS}=0V, I_D=-250\mu A$
Zero gate voltage drain current	I_{DSS}			-500	nA	$V_{DS}=-100V, V_{GS}=0V$
Gate-body leakage current	I_{GSS}			± 100	nA	$V_{DS}=0V, V_{GS}=\pm 20V$
Gate-threshold voltage	$V_{GS(th)}$	-2.0		-4.0	V	$V_{DS}=V_{GS}, I_D=-250\mu A$
Drain-source on-resistance(5)	$R_{DS(ON)}$			0.35	Ω	$V_{GS}=-10V, I_D=-1.4A$
				0.45	Ω	$V_{GS}=-6V, I_D=-1.2A$
Forward Trans-conductance (5,6)	g_{fs}		2.8		S	$V_{DS}=-15V, I_D=-1.4A$
Diode Forward Voltage (5)	V_{SD}	-0.85	-0.95		V	$I_S=-1.7A, V_{GS}=0V$
Reverse Recovery Time(6)	t_{rr}		33		nS	$I_f=-1.5A, di/dt=100A/\mu s$
Reverse Recovery Charge(6)	Q_{rr}		48		nC	
Input capacitance (6)	C_{iss}		424		pF	$V_{DS}=-50V, V_{GS}=0V, f=1MHz$
Output capacitance(6)	C_{oss}		36.6		pF	
Reverse transfer capacitance(6,7)	C_{rss}		29.8		pF	
Total Gate Charge(6,7)	Q_g		7.1		nC	$V_{DS}=-50V, V_{GS}=-6.0V, I_D=-1.4A$
			10.7		nC	
Gate-Source Charge(6,7)	Q_{gs}		1.7		nC	$V_{DS}=-50V, V_{GS}=-10V, I_D=-1.4A$
Gate-Drain Charge(6,7)	Q_{gd}		3.8		nC	
Turn-on delay time(6,7)	$t_{d(on)}$		3.0		nS	
Turn-on rise time(6,7)	t_r		3.5		nS	$V_{DD}=-15V, I_D=-1A, V_{GS}=-10V, R_G=6.0\Omega$
Turn-off delay time(6,7)	$t_{d(off)}$		13.4		nS	
Turn-off fall time(6,7)	t_f		7.2		nS	

Notes: 1. For a device surface mounted on 25mm x 25mm x 1.6mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions; the device is measured when operating in a steady-state condition.

2. Same as Note1, except the device is measured at $t \leq 10$ seconds.

3. Same as Note1, except the device is pulsed with $D=0.02$ and pulse width 300 μs . The pulse current is limited by the maximum junction temperature.

4. Thermal resistance from junction to solder-point (at the end of the drain lead).

5. Measured under pulsed conditions. Pulse width $\leq 300\mu s$; duty cycle $\leq 2\%$.

6. For design aid only, not subject to production testing.

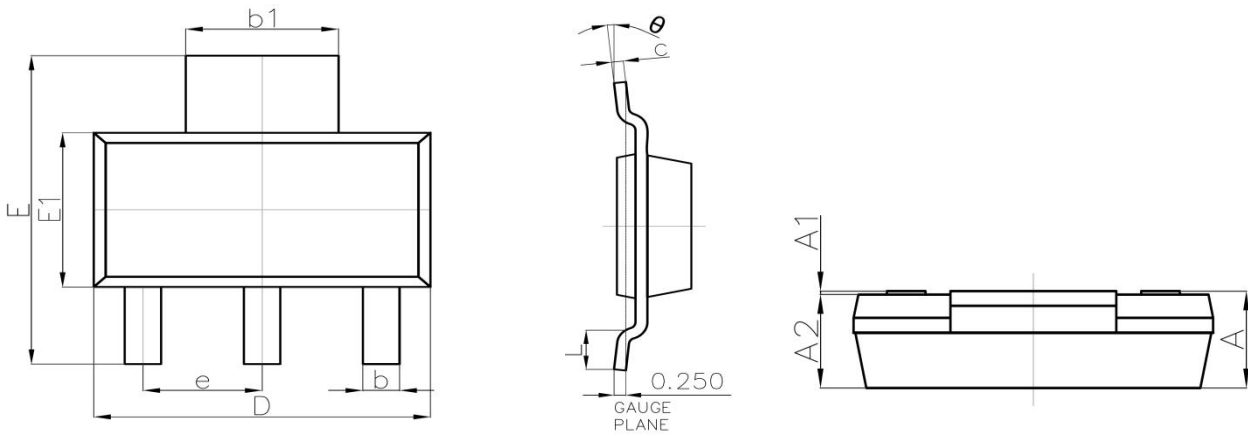
7. Switching characteristics are independent of operating junction temperatures.

P-CHANNEL HIGH VOLTAGE MOSFET

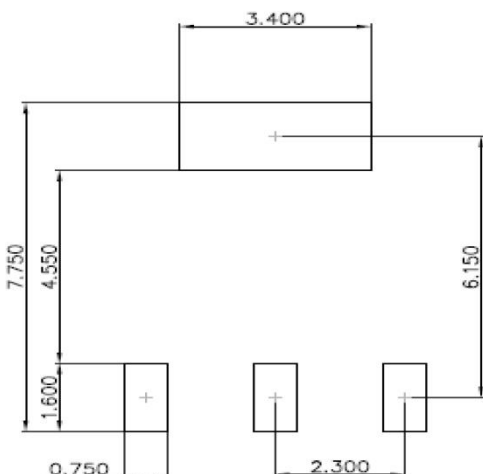
Typical Characteristics

P-CHANNEL HIGH VOLTAGE MOSFET

P-CHANNEL HIGH VOLTAGE MOSFET

P-CHANNEL HIGH VOLTAGE MOSFET
SOT-223 Package Outline Dimensions


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	—	1.800	-----	0.071
A1	0.020	0.100	0.001	0.004
A2	1.500	1.700	0.059	0.067
b	0.660	0.840	0.026	0.033
b1	2.900	3.100	0.114	0.122
c	0.230	0.350	0.009	0.014
D	6.300	6.700	0.248	0.264
E	6.700	7.300	0.264	0.287
E1	3.300	3.700	0.130	0.146
e	2.300(BSC)		0.091(BSC)	
L	0.750	-----	0.030	-----
θ	0°	10°	0°	10°

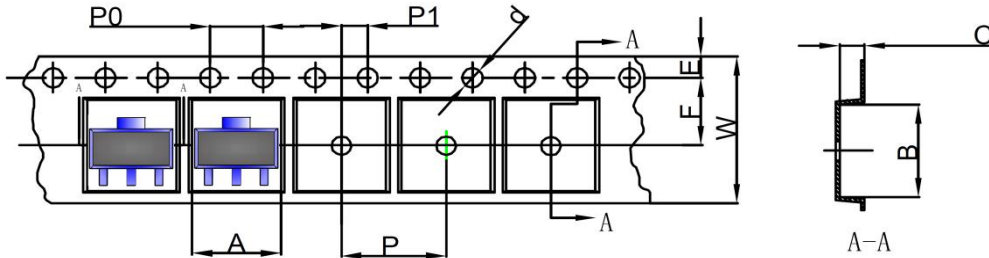
SOT-223 Suggested Pad Layout

Note:

1. Controlling dimension: in millimeters
2. General tolerance: $\pm 0.05\text{mm}$
3. The pad layout is for reference purposes only

P-CHANNEL HIGH VOLTAGE MOSFET

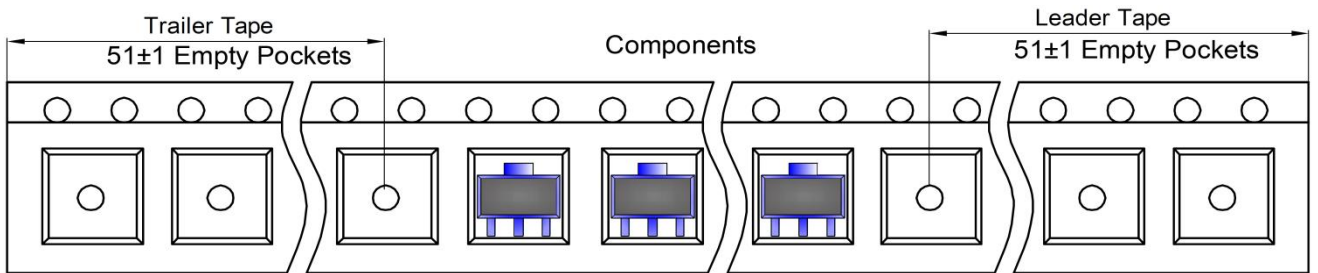
SOT-223 Tape and Reel

SOT-223 Embossed Carrier Tape

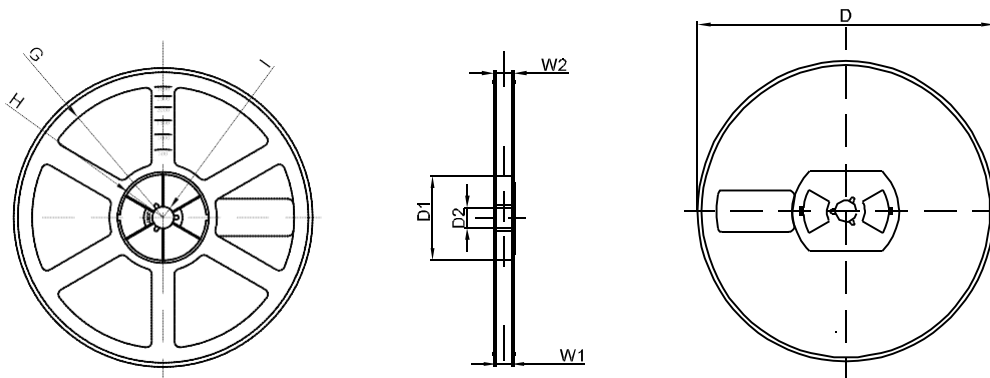


DIMENSIONS ARE IN MILLIMETER										
TYPE	A	B	C	d	E	F	P0	P	P1	W
SOT-223	6.765	7.335	1.88	Ø1.50	1.75	5.50	4.00	4.00	2.00	12.00
TOLERANCE	±0.1	±0.1	±0.1	±0.1	±0.1	±0.1	±0.1	±0.1	±0.1	±0.1

SOT-223 Tape Leader and Trailer



SOT-223 Reel



DIMENSIONS ARE IN MILLIMETER								
REEL OPTION	D	D1	D2	G	H	I	W1	W2
13" DIA	Ø330.00	100.00	13.00	R151.00	R56.00	R6.50	12.40	17.60
TOLERANCE	±2	±1	±1	±1	±1	±1	±1	±1